

IFW 2823

**STATEMENT UNDER 37 CFR 1.97(e) ACCOMPANYING
INFORMATION DISCLOSURE STATEMENT**

Docket No.
END920010026US1

In Re Application Of: **Bernier, et al.**

JUN 27 2006

Application No. 09/885,853	Filing Date 06/20/2001	Examiner William D. Coleman	Customer No. 30449	Group Art Unit 2823	Confirmation No. 4080
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Invention: **EXTENSION OF FATIGUE LIFE FOR C4 SOLDER BALL TO CHIP CONNECTION**

COMMISSIONER FOR PATENTS:

This is a statement under the provisions of 37 CFR 1.97(e) in the above-identified application.

Check applicable statement herebelow:

Statement Under 37 CFR 1.97(e)(1)

- ☒ Each item of information contained in the accompanying Information Disclosure Statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the Information Disclosure Statement.

Statement Under 37 CFR 1.97(e)(2)

- ☐ No item of information contained in the accompanying Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application, and, to the knowledge of the undersigned person, after making reasonable inquiry, no item of information contained in the accompanying Information Disclosure Statement was known to any individual designated in 37 CFR 1.56(c) more than three months prior to the filing of the Information Disclosure Statement.


Signature

Dated: **06/23/2006**

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Signature of Person Mailing Correspondence

Tina Holford

Typed or Printed Name of Person Mailing Correspondence

CC:

INFORMATION DISCLOSURE CITATION <i>(Use several sheets if necessary)</i>				ATTY DOCKET NO. END920010026US1		APPLICATION NO. 09/885,853	
				APPLICANT(S) Bernier, et al.			
				FILING DATE 06/20/2001		GROUP ART UNIT 2823	
U.S. PATENT DOCUMENTS							
*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
U.S. PATENT APPLICATION PUBLICATIONS							
*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
FOREIGN PATENT DOCUMENTS							
		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION
							YES NO
		PUPA 03-218644	09/26/1991	JP			
		PUPA 09-153521	06/10/1997	JP			
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)							
EXAMINER				DATE CONSIDERED			

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

USA. Pending
***** Information Materials for IDS *****

To END IP Law Docket Number END9-2001-0026 Date June/06/06

Prepared by Yasuhiro NOGUCHI Date of JPO Office Action May/16/06

Applied Art (The following reference(s) were cited by JPO Examiner as Prior art to the following JP claims)

Ref.	Patent Document No. or Title	Publication Date (MM/DD/YY)	English abs. or counterpart document available (Y/N)	JP claim(s)
A	PUPA 03-218644	09/26/91	Y	1-18
B	PUPA 09-153521	06/10/97	Y	2-18
C				
D				
E				
F				

<NOTE> to be continued ☐
 ◇ PUPA : Published Unexamined Patent Application ◇ PEPA : Published Examined Patent Application
 ◇ PUUMA : Published Unexamined Utility Model Application ◇ PEUMA : Published Examined Utility Model Application
 ◇ JP : Japanese Patent ◇ * : Reference being filed before and published after the priority application date of the subject docket

Background Art (The following reference(s) were cited but not applied to the JP claims.)

Ref.	Patent Document No. or Title	Ref.	Patent Document No. or Title
bgA		bgD	
bgB		bgE	
bgC		bgF	

Comment, if any : to be continued ☐